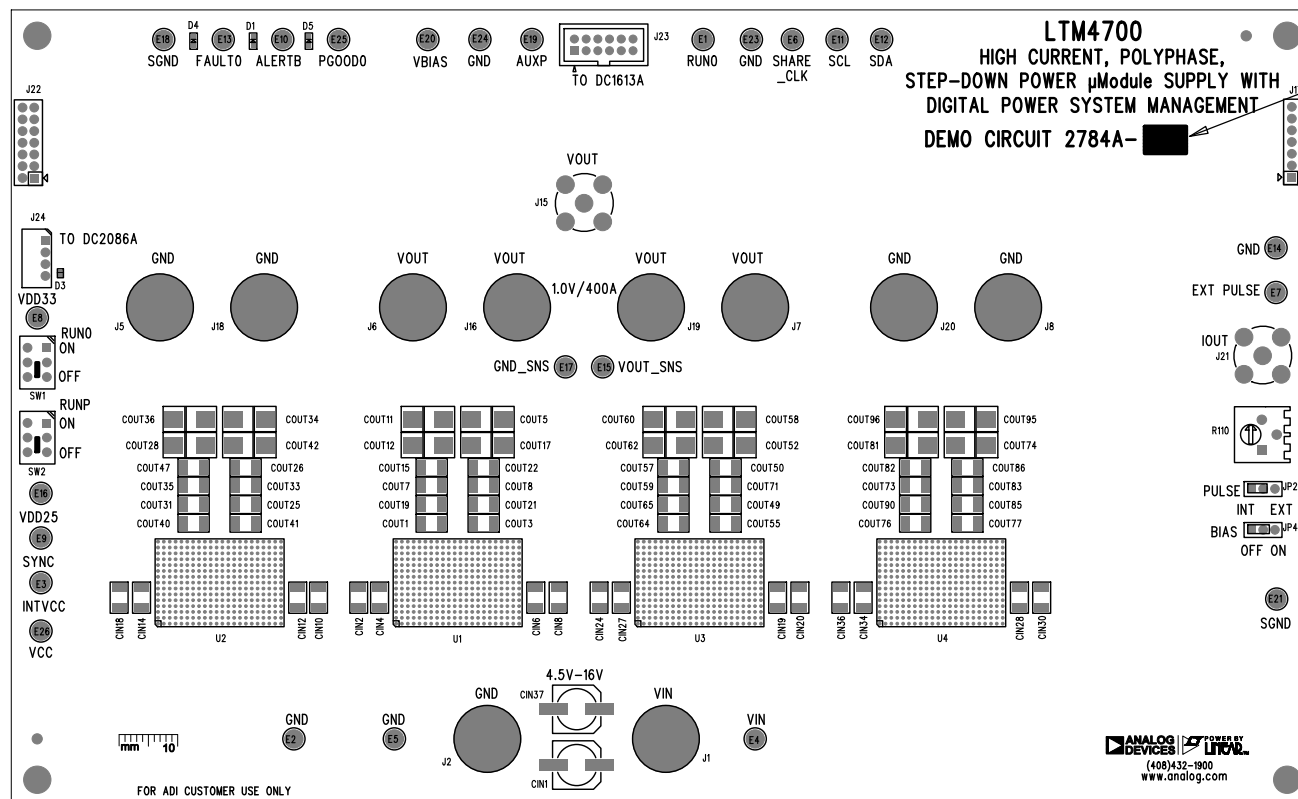


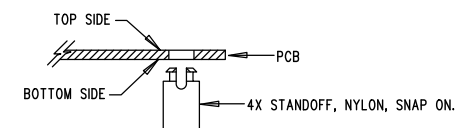
REVISION HISTORY			
ECO	REV	DESCRIPTION	APP. ENG. DATE
-	3	PRODUCTION	HZ 10-26-18





LAYER 1 - TOP SIDE

NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL STANDOFFS AS SHOWN BELOW:



8. SEE THE BILL OF MATERIALS TO MARK THE APPROPRIATE ASSEMBLY TYPE WITH BLACK PERMANENT MARKER.

APPROVALS		 ANALOG DEVICES		 POWER BY LINEAR™ (408)432-1900 www.Analog.com FOR ADI CUSTOMER USE ONLY	
PCB DES.	LT	TITLE: TOP ASSEMBLY DRAWING HIGH CURRENT, POLYPHASE, STEP-DOWN POWER μ Module SUPPLY WITH DIGITAL POWER SYSTEM MANAGEMENT			
APP ENG.	HZ				
		SIZE	IC NO. LTM4700EY	REV. 3	
		N/A	DEMO CIRCUIT 2784A(A,B,C)		
SCALE = NONE		FILENAME: DC2784A-3.PCB		SHT 1 OF 2	